PCN Number:	PCN#20250508000.1A	**PCN Date:**	June 09, 2025
Title:	Qualification of additional Assembly sites for select TSSOP devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	August 06, 2025	**Sample requests accepted until:**	August 08, 2025*

***Sample requests received after August 08, 2025 will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Revision A is to add a mount compound & mold compound that were not included on the original PCN notification. These new materials are highlighted and bolded below.

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

TSSOP Build Sites	
Assembly Sites	TAI, MLA, TIEMA, ASEHAT, CAR, TFME, CDAT
Mount Compound	4147858
	4211470
	4207768
	4208458
	4042500
	4213245
	SID#434165
	SID#EY1000063
Mold Compound	4211471
	4206193
	4228573
	4226323
	4209002
	SID#438518
	SID#EN2000508
	SID#R-31
Leadframe Finish	NiPdAu, Matte Sn
Bond Wire (mil)	AU (0.96), CU (0.7,0.8, 0.96, 1.0,1.15)

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TAI	TAI	TWN	Chung Ho, New Taipei City
MLA	MLA	MYS	Kuala Lumpur
TIEMA	CU6	MYS	Melaka
CAR	CAR	MYS	Ipoh
ASESHAT	ASH	CHN	Shanghai
TFME	NFM	CHN	Chongchuan
CDAT	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)

Product Affected:

CD4001BPWR*	SN65C3221PWR*	SN74HC4040PWR*	TLC2264CPWR*
CD4043BPWR*	SN65C3232EPWR*	SN74HC74PWR*	TLC2274CPWR*
CD4047BPWR*	SN65C3232PWR*	SN74HC86PWR*	TLC274IPWR*
CD4050BPWR*	SN74AXC4T245PWR*	SN74HCS08PWR*	TLV2464AIPWR*
CD4081BPWR*	SN74AXC4T774PWR*	SN74HCS157PWR*	TLV2464CPWR
CD4094BPWR*	SN74CBTLV3126PWR*	SN74HCS20PWR*	TLV4333IPWR*
CD4511BPWR*	SN74CBTLV3251PWR*	SN74HCS365PWR*	TLV6004IPWR*
CD74HC08PWR*	SN74CBTLV3257PWR*	SN74HCS4075PWR*	TLV9004IPWR
CD74HC14PWR*	SN74GTL2014PWR*	SN74HCT02PWR*	TMUX1112PWR*
CD74HC238PWR*	SN74GTLP1394PWR*	SN74HCT139PWR*	TMUX1113PWR*
CD74HC30PWR*	SN74HC03PWR*	SN74HCT32PWR*	TMUX1133PWR*
CD74HC4002PWR*	SN74HC10PWR*	SN74HCT74PWR*	TMUX1208PWR*
CD74HC4024PWR*	SN74HC11PWR*	SN74LV05APWR*	TMUX1209PWR*
CD74HC4075PWR*	SN74HC126PWR*	SN74LV157APWR*	TMUX1511PWR*
CD74HCT14PWR*	SN74HC132PWR*	SN74LV174APWR*	TMUX1574PWR*
DRV8847PWR*	SN74HC139PWR*	SN74LV20APWR*	TMUX6104PWR*
INA4180A4IPWR*	SN74HC14APWR*	TCA6408APWR*	TMUX6113PWR*
LMK1C1108PWR*	SN74HC153PWR*	TCA9534APWR*	TMUX6136PWR*
MAX202IPWR	SN74HC157PWR*	TCA9534PWR*	TRS3221ECPWR*
MAX232EIPWR*	SN74HC21PWR*	TCA9538PWR*	TRS3221EIPWR*
MAX3221ECPWR*	SN74HC251PWR*	TCA9543APWR*	TRS3232IPWR*

MAX3232ECPWR*	SN74HC257PWR*	TCA9554APWR*	TRSF3232EIPWR*
OPA1679IPWR*	SN74HC259PWR*	TCA9554PWR*	TS5V330CPWR*
OPA4991IPWR*	SN74HC365PWR*	TL064CPWR*	TUSB1106PWR*
PCA9534APWR*	SN74HC393PWR*	TL084CPWR*	TXU0104PWR*
SN65C3221EPWR*	SN74HC4020PWR*	TL974IPWR*	TXU0204PWR*

* G4 part numbers are available and will remain on NiPdAu flows. This PCN does not apply to existing G4 materials. Please visit TI's labeling and symbolization page for more information on material designators.

TEXAS INSTRUMENTS

TI Information
Selective Disclosure

TSSOP Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	MLA TCA6416PW	TIEMA LM5037MTNOPB
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (DAC70004IPW)	3/66/0 (LDC1000PW)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TFME SN74HCS74PW	TAI TLC59116ITPWRQ1 LDC5072A0PWQ1
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (SN0901056B1PW)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	ASESHAT LSF0108QPWRQ1 LM2902PW	CAR BQ26501PW TPS53125PW PGA309AIPW
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH	96 hours Or 264 hours	3/231/0	3/231/0
	Or Temperature Humidity Bias, 85C/85%RH	Or 1000 hours		
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TL1431CPW)	3/66/0 (DRV603PW)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	CDAT MAX202IPW
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0 (Note 1)
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0
MQ	Manufacturability	-	Pass

Note 1 – bHAST performed on CD4060BPWR (MLA), with 1 lot performed TMUX1308QPWRQ1 (CDAT) as part of enterprise qualification.

Devices LSF0108QPWRQ1, LM2902PW, SN74HCS74PW, TPS53125PW, TCA6416PW, LM5037MTNOPB, TLC59116ITPWRQ1, PGA309AIPW, MAX202IPW, CD4060BPWR qualified at MSL1 rating. Devices BQ26501PW qualified at MSL2 and device LDC5072A0PWQ1 qualified at MSL3.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable.
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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